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First Call For Papers

2023 IEEE 15th International Conference on ASIC

Oct. 24-27, 2023, Platinum Hanjue Hotel
Nanjing , China

Sponsored by
Co-Sponsored by

IEEE Beijing Section
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2023 IEEE 15th International Conference on ASIC (ASICON 2023) will be held in Nanjing, China, during Oct.24-27, 2023. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper Award & Outstanding Young Scholar Paper Award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

The Scope of the Conference

Papers are solicited in, but not limited to, the following:

I. Integrated Circuits and Design Techniques

[1] Analog IC

- Amplifiers,
- Data converters (ADCs and DACs)
- Power management ICs and Energy Harvesting
- Clock generator,

[2] Digital IC

- Low power technique
- CPU, MCU, GPU, Embedded processors and DSP
- Machine learning IC
- Chaos/neural/fuzzy-logic circuits
- Programmable devices (PLD, EPLD, HDPLD, FPGA, etc)
- NOC

[3] Wireless, Wireline telecommunication and Optic Communication IC

- RF block circuits (LNA, Mixer, PA, Integrated Antenna and Switches),
- RF Transceiver (Transmitter, receiver, PLL in RF transceiver), RFID
- millimeter-wave circuits
- Seders
- THz circuits,
- Laser Driver, TIA, CDR,

[4] Memory

- DRAM & SRAM
- Flash memory
- Ferroelectric memory
- Phase change memory, RRAM, MRAM
- Novel memory

[5] Sensor, Image Processing and Bio-medical IC

- Sensor circuits
- Graph theory and computing
- Biomedical circuits and systems
- Wearable systems

II. FPGA

[6] FPGA and DSP

